


TYPICAL DEVICE CHARACTERISTICS
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

PARAMETER	SYMBOL	VALUE	UNITS
Operating Temperature	T_L	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P_{PP}	500	Watts

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER (Note 1-5)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ $I_p = 1A$ V_c VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ $I_p = 5A$ V_c VOLTS	MAXIMUM LEAKAGE CURRENT @ V_{WM} I_D μA	MAXIMUM CAPACITANCE @0V, 1MHz C pF
USB50803	GA	3.3	4.5	8.0	11.0	125	3
USB50803C	UGA	3.3	4.5	8.0	11.0	125	3
USB50805	GB	5.0	6.0	10.8	13.0	20	3
USB50805C	UGB	5.0	6.0	10.8	13.0	20	3
USB50812	GC	12.0	13.3	19.0	26.0	1	3
USB50812C	UGC	12.0	13.3	19.0	26.0	1	3
USB50815	GD	15.0	16.7	24.0	32.0	1	3
USB50815C	UGD	15.0	16.7	24.0	32.0	1	3
USB50824	GE	24.0	26.7	43.0	57.0	1	3
USB50824C	UGE	24.0	26.7	43.0	57.0	1	3

NOTES

1. Part numbers with a "C" suffix are bidirectional devices, i.e., USB50803C.
2. Do not apply surge in the forward direction of the TVS.
3. PIV typically greater than 100V for each rectifier diode.
4. Electrical characteristics apply to pins 8 to 1, 2 to 7, 6 to 3 and 4 to 5 for the bidirectional configuration.
5. Electrical characteristics apply to pins 7 to 2 and 5 to 4 for the unidirectional configuration.

TYPICAL DEVICE CHARACTERISTICS

FIGURE 1
PEAK PULSE POWER VS PULSE TIME

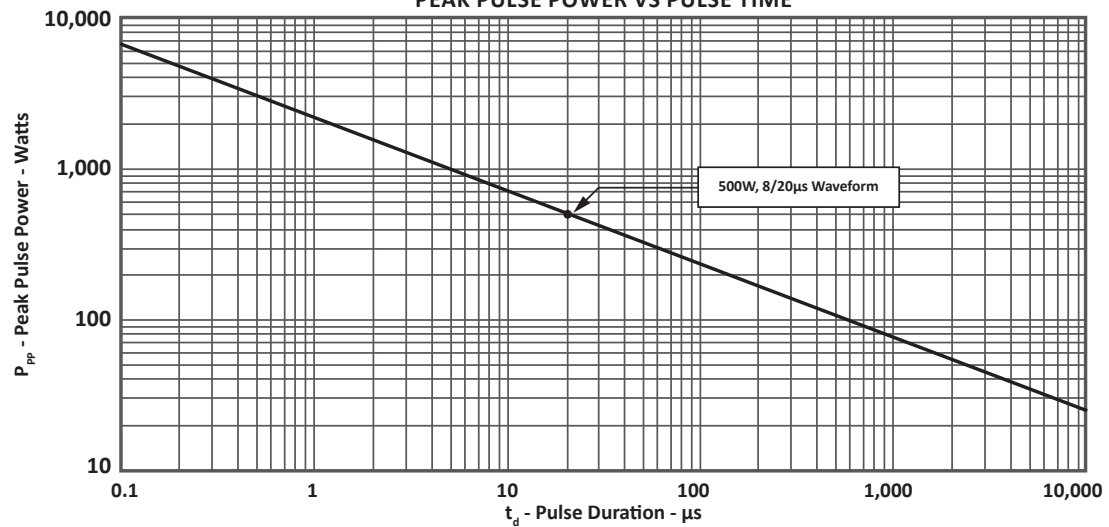


FIGURE 2
PULSE WAVE FORM

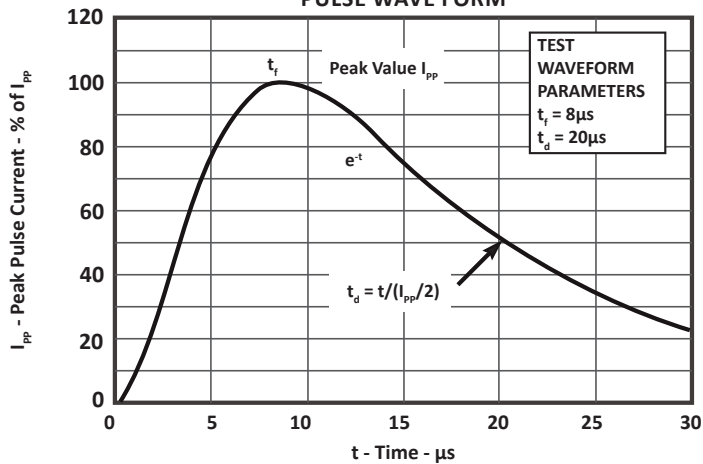
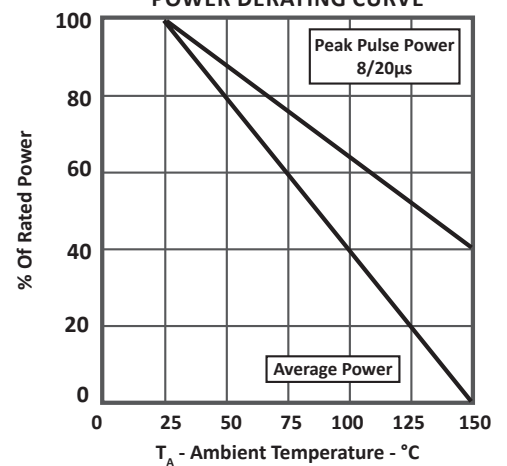


FIGURE 3
POWER DERATING CURVE

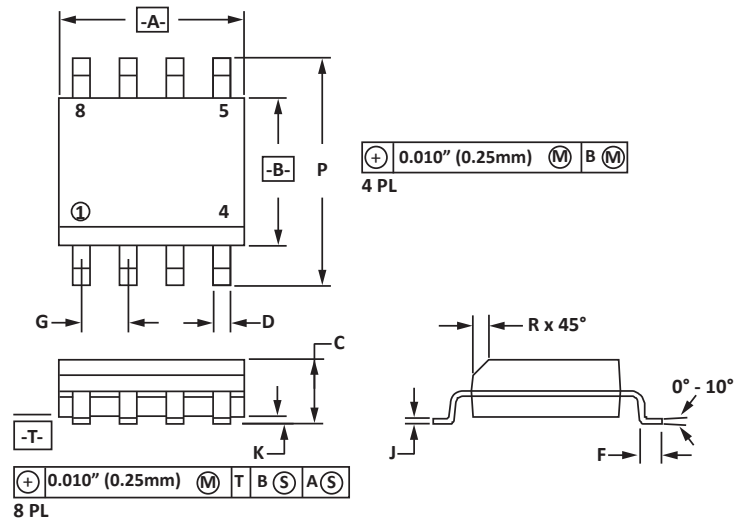


SO-8 PACKAGE INFORMATION

OUTLINE DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.196
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.05 BSC	
J	0.18	0.25	0.007	0.009
K	0.10	0.25	0.004	0.008
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

NOTES

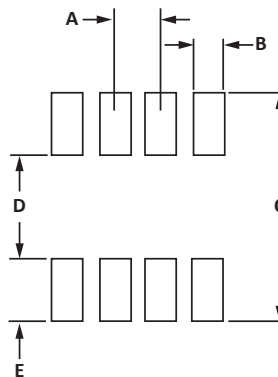
1. -T- = Seating plane and datum surface.
2. Dimensions "A" and "B" are datum.
3. Dimensions "A" and "B" do not include mold protrusion.
4. Maximum mold protrusion is 0.015" (0.380mm) per side.
5. Dimensioning and tolerances per ANSI Y14.5M, 1982.
6. Dimensions are exclusive of mold flash and metal burrs.



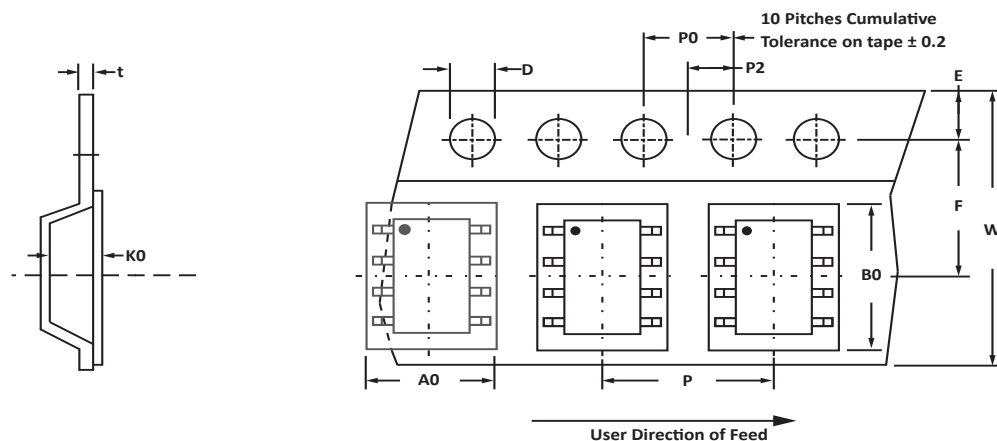
PAD LAYOUT DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.14	1.40	0.045	0.055
B	0.64	0.89	0.025	0.035
C	6.22	-	0.245	-
D	3.94	4.17	0.155	0.165
E	1.02	1.27	0.040	0.050

NOTES

1. Controlling dimension: inches.



TAPE AND REEL



SPECIFICATIONS

REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	tmax
178mm (7")	12mm	6.50 ± 0.10	5.40 ± 0.10	2.00 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	5.50 ± 0.05	12.00 ± 0.30	4.00 ± 0.12	2.00 ± 0.10	8.00 ± 0.10	0.25

NOTES

1. Dimensions are in millimeters.
2. Surface mount product is taped and reeled in accordance with EIA-481.
3. Suffix - T7 = 7" Reel - 1,000 pieces per 12mm tape.
4. Suffix - T13 = 13" Reel - 2,500 pieces per 12mm tape.
5. Bulk product shipped in tubes of 98 pieces per tube.
6. Marking on Part - marking code (see page 2), date code, logo and pin one defined by dot on top of package.

ORDERING INFORMATION

BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
USB0508xx/USB0508xxC	n/a	-T7	1,000	7"	98
USB0508xx/USB0508xxC	n/a	-T13	2,500	13"	98

This device is only available in a Lead-Free configuration.

COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

CONTACT US

Corporate Headquarters

2929 South Fair Lane
Tempe, Arizona 85282
USA

By Telephone

General: 602-431-8101
Sales: & Marketing: 602-414-5109
Customer Service: 602-414-5114
Product Technical Support: 602-414-5107

By Fax

General: 602-431-2288

By E-mail:

Asia Sales: asiasales@protekdevices.com
Europe Sales: europesales@protekdevices.com
U.S. Sales: ussales@protekdevices.com
Distributor Sales: distysales@protekdevices.com
Customer Service: service@protekdevices.com
Technical Support: support@protekdevices.com

ProTek Devices (Asia Pacific) Pte. Ltd.

8 Ubi Road 2, #06-19
Zervex
Singapore - 408538
Tel: +65-67488312
Fax: +65-67488313

Web

www.protekdevices.com

COPYRIGHT © ProTek Devices 2009 - This literature is subject to all applicable copyright laws and is not for resale in any manner.

SPECIFICATIONS: ProTek reserves the right to change the electrical and or mechanical characteristics described herein without notice.

DESIGN CHANGES: ProTek reserves the right to discontinue product lines without notice and that the final judgement concerning selection and specifications is the buyer's and that in furnishing engineering and technical assistance. ProTek assumes no responsibility with respect to the selection or specifications of such products. ProTek makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ProTek assume any liability arising out of the application or use of any product or circuit and specifically disclaims any and all liability without limitation special, consequential or incidental damages.

LIFE SUPPORT POLICY: ProTek Devices products are not authorized for use in life support systems without written consent from the factory.